



# Usage of SystemC-AMS MDVP for virtual prototyping of a MEMS application

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- Virtual Prototyping: the Objective
- Application description
- The MEMS sensors : modeling and MoCs
- Coherent Stimuli: the challenge
- MoC considerations & Conclusions

# Objective

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- SystemC AMS and Multi-Domain Virtual Prototyping (MDVP) **virtual platforms** will allow **costs** and **time-to-market reduction**
- The architect perspective:
  - HW/SW partitioning
  - HW resources specification
- The SW developer perspective
  - **Early development/debug of the embedded SW before prototypes** (with analog and mechanical parts)
  - **Embedded SW validation for families of object movements and corners** (Temperature)
  - **Power efficient control/readout of MEMS** (HW resources optimization)
- Virtual platform used as **demonstrator** for customers

# Application description



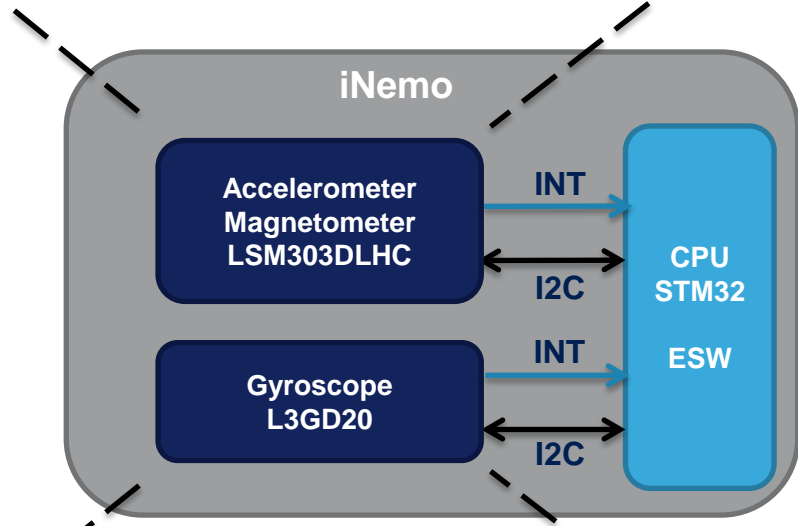
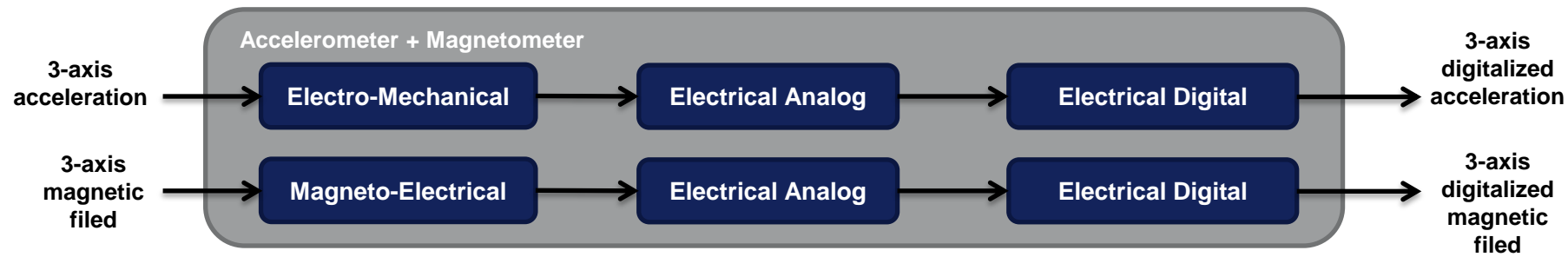
- iNemo board embedding:
  - Accelerometer/Magnetometer
  - Gyroscope
- Motion detection for:
  - Gesture recognition
  - Motion tracking
  - Fall detection
- Through:
  - Sensor fusion algorithms



# Motion detection

**LEGEND:**

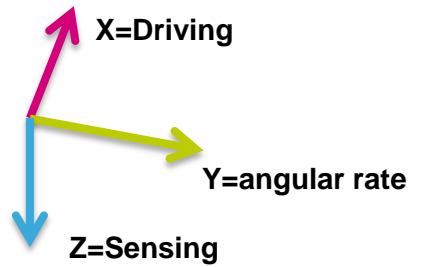
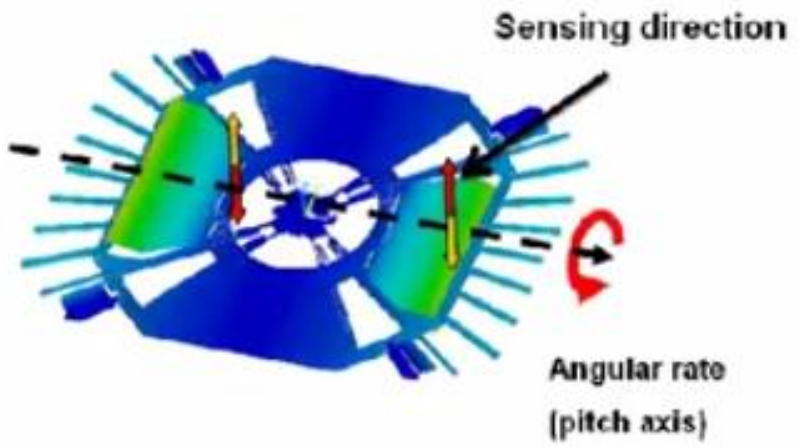
- SystemC AMS+TLM
- C Embedded SW



# MEMS sensor: Gyroscope example

- Sensor functioning overview
- TDF MoC model
- Bond-Graph MoC model proposal
- Non-linear refined model from FEA
- Digital on-chip processing

# Gyroscope functioning overview



Coriolis force:  $F_C = -2 m \Omega \times v$

Where: 
$$\Omega \times v = \begin{vmatrix} i & j & k \\ \Omega_x & \Omega_y & \Omega_z \\ v_x & v_y & v_z \end{vmatrix} = \begin{pmatrix} \Omega_y v_z - \Omega_z v_y \\ \Omega_z v_x - \Omega_x v_z \\ \Omega_x v_y - \Omega_y v_x \end{pmatrix}$$

|
|
—  $F_{Cz}$  on Sensing axis

|
|

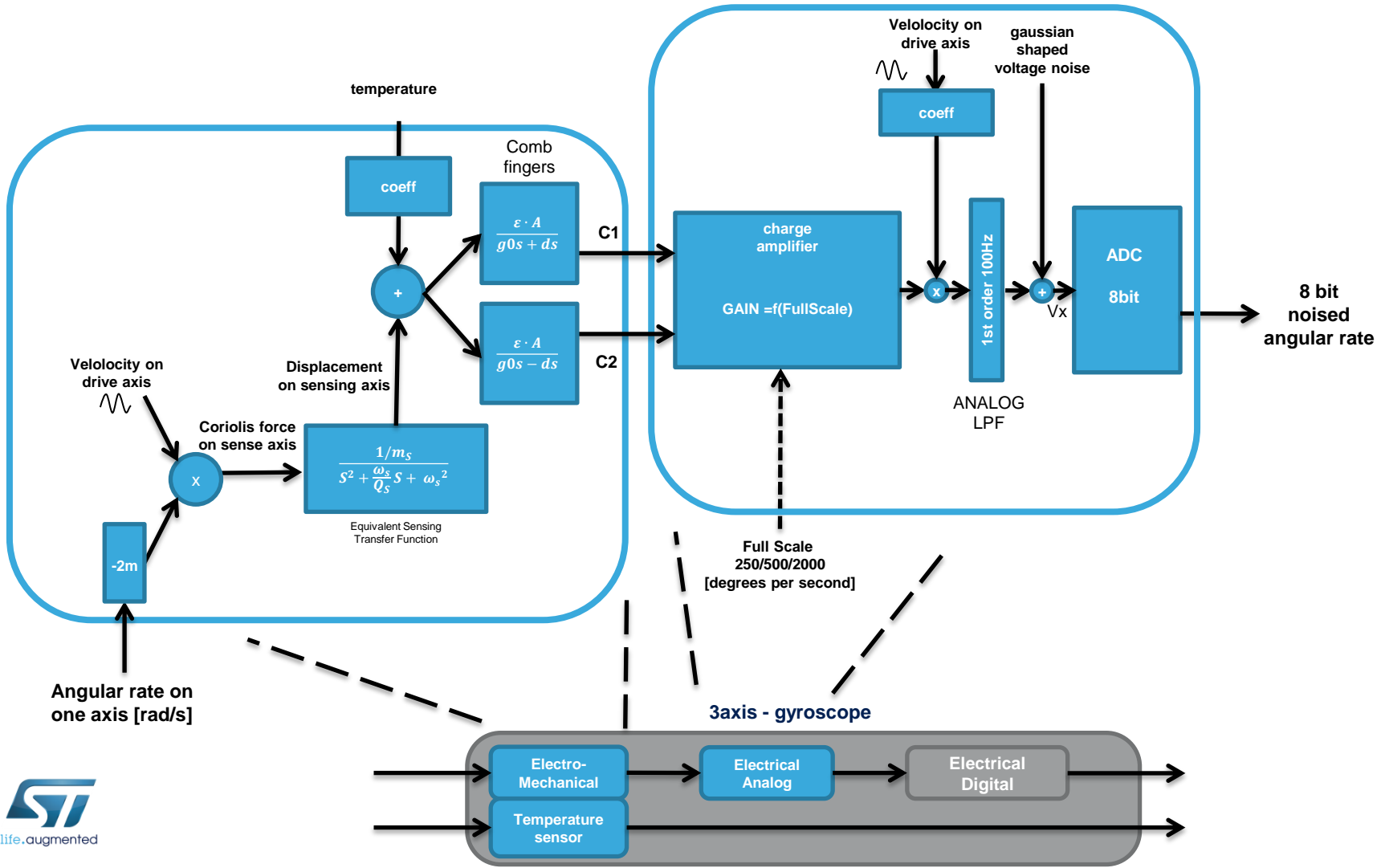
Unwanted term
Desired term

# Gyroscope TDF model

**LEGEND:**

- SystemC AMS TDF
- SystemC TLM

- Time step to be specified by user based on his knowledge of the system and independently from signal dynamics



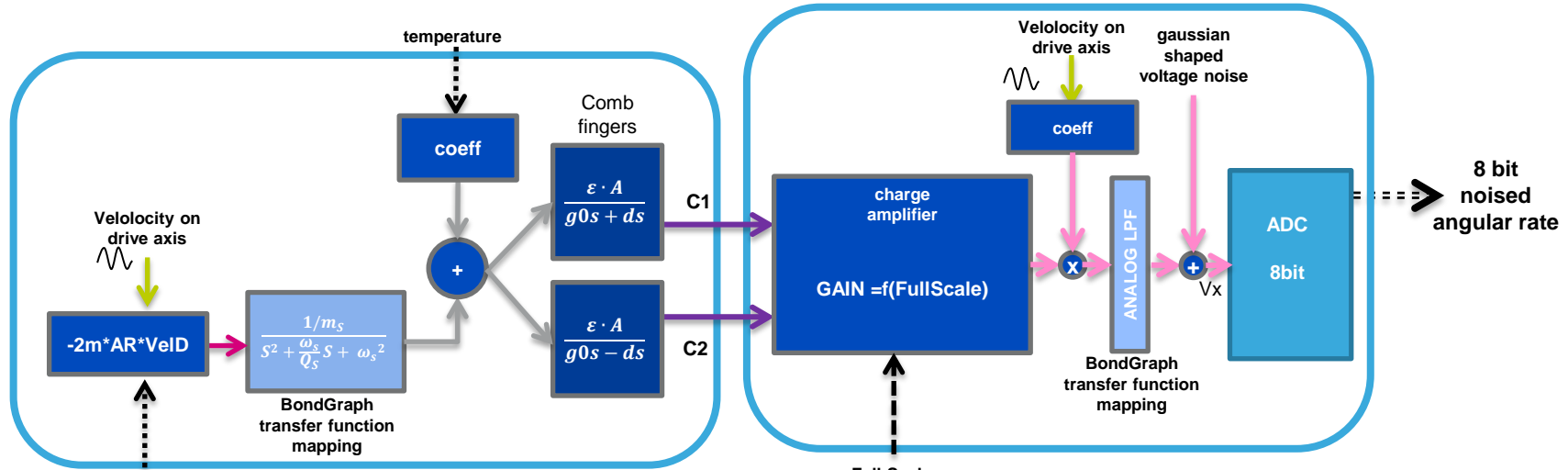


# Bond-Graph MoC model proposal

**LEGEND:**

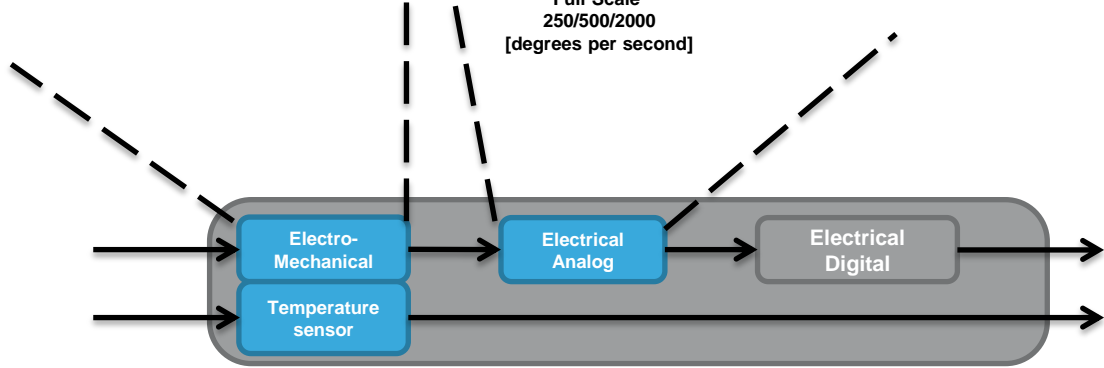
- SystemC MDVP BlockDiagram
- SystemC MDVP BondGraph
- SystemC AMS TDF

- Signal typing (connectivity check)
- Time step adapted to signal dynamics (time step max specified)



Full Scale  
250/500/2000  
[degrees per second]

Angular rate on one axis [rad/s]



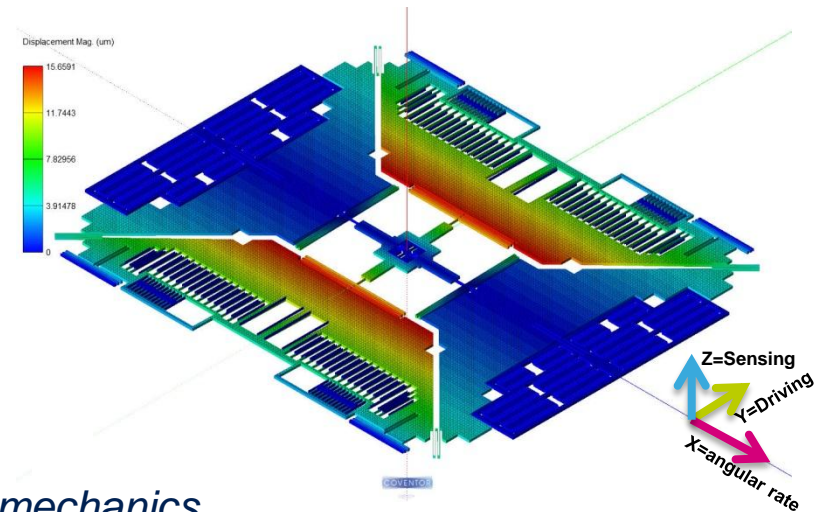
scax\_signal

- Force (pink arrow)
- Velocity (green arrow)
- Displacement (grey arrow)
- Capacitance (purple arrow)
- Voltage (pink arrow)
- Double (thickness)
- Int (thickness)
- SC (dashing)
- TDF (dashing)

# Non-linear refined model from FEA

Under development in MEMS+<sup>®</sup> by Coventor

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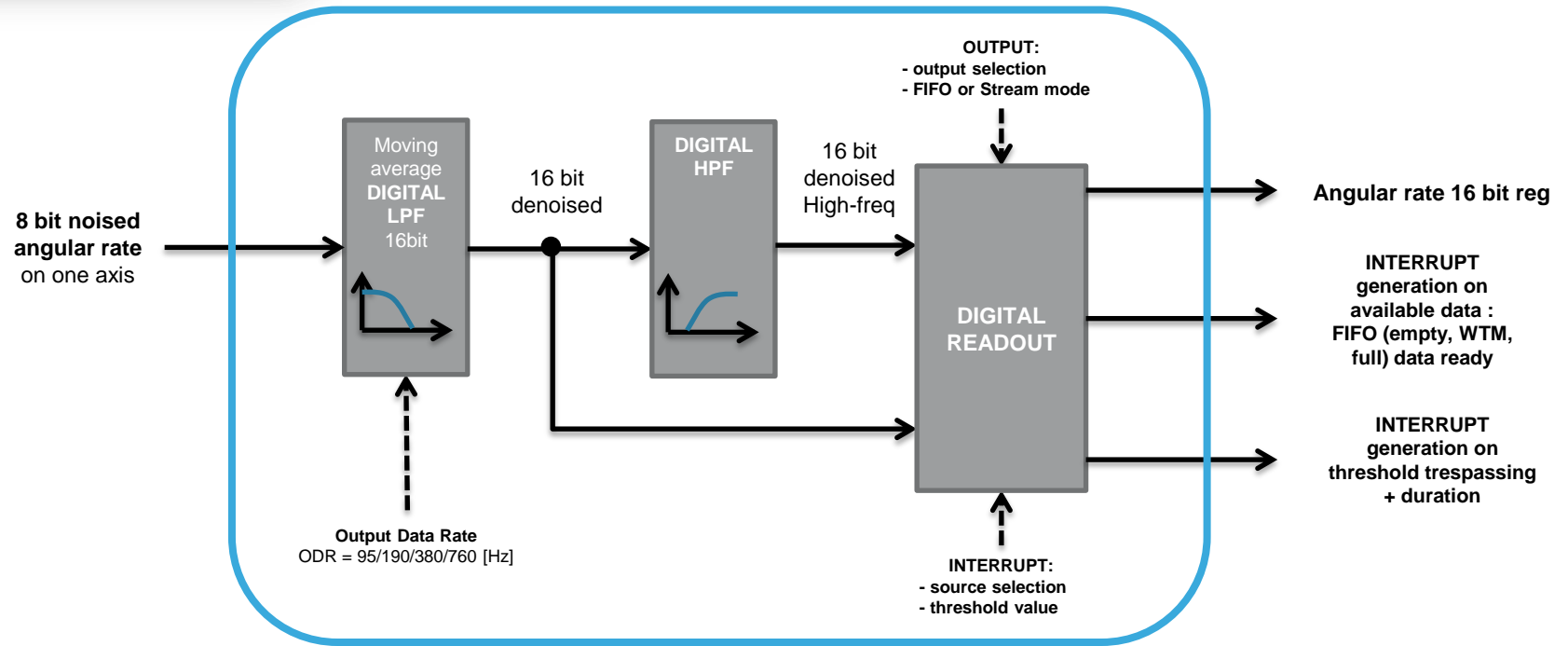
- Component-based Finite Element Analysis (FEA)
- Coupling multiple physical domains *electrostatics, mechanics...*
- Based on state-space system *inherent to MEMS+<sup>®</sup> 3D model*
  - Model-Order Reduction thanks to state-number reduction
  - Non-linearity thanks to the interpolation of state-space linearizations
- Integration in SystemC-AMS
  - Custom TDF module with specific *processing()* method
  - Ongoing tests with Dynamic TDF (potential speed-up of the computation)

# Register bank

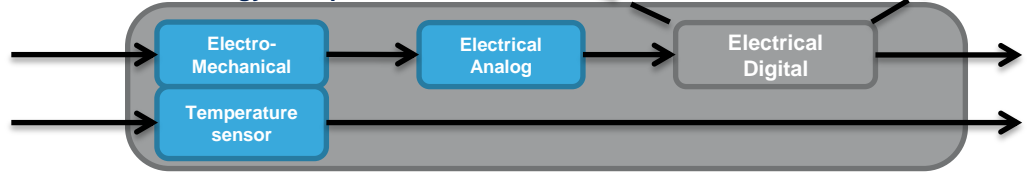
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			Hex	Binary	
Reserved (do not modify)	Table 14		00 - 1F	--	--
CTRL_REG1_A	Table 14	rw	20	010 0000	00001111
CTRL_REG2_A	Table 14	rw	21	010 0001	00000000
CTRL_REG3_A	Table 14	rw	22	010 0010	00000000
CTRL_REG4_A	Table 14	rw	23	010 0011	00000000
CTRL_REG5_A	Table 14	rw	24	010 0100	00000000
CTRL_REG6_A	Table 14	rw	25	010 0101	00000000
REFERENCE_A	Table 14	rw	26	010 0110	00000000
STATUS_REG_A	Table 14	r	27	010 0111	00000000

CONFIG registers

# Digital on-chip processing



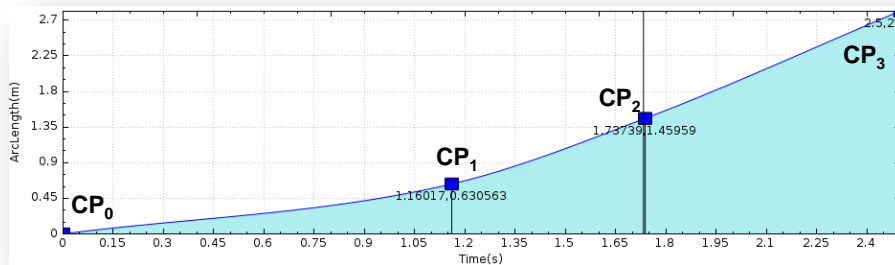
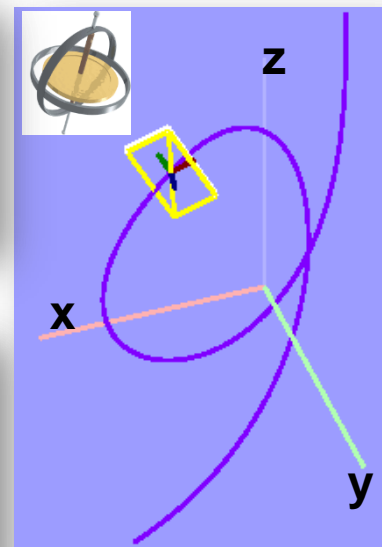
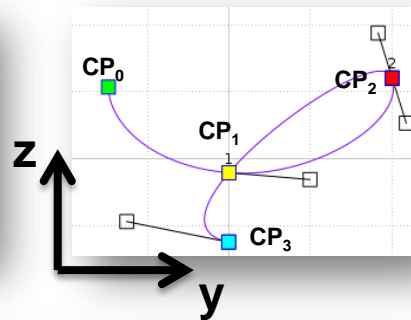
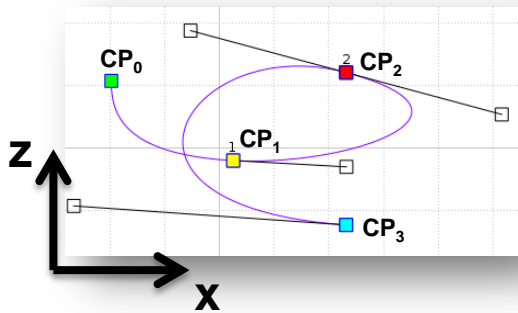
## 3axis - gyroscope



# Coherent stimuli generation

## • Internal tool for

- Object trajectory definition (both 3D path+temporal aspect)
- Object orientation evolution along the trajectory (through Control Points CP)
- Generate xml file to provide the stimuli to SystemC MEMS simulation



```

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<tS>0.0004</tS>
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<deltaAngle>...</deltaAngle>
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<temper>27</temper>
</p>

```

# MoC considerations

MoC	Time step	Advantages	Drawbacks
TDF	constant & user defined	Easy to code	time step - constant → non-optimal for analog behaviors and closed loops - user defined
Bond Graph	dynamic max limit to be specified	Dynamic time step → faster simulation  Good accuracy on closed-loops (delay needed with TDF)  Simulator accuracy tunable	Not trivial to code in current PoC
Refined model from FEA (TDF)	constant in current PoC & user defined	High accuracy from FEA (driving voltages + non-linearities)  Automatic code generation	Code interpreteability  time step - user defined

Bond Graph MoC and MEMS+ model are ongoing developments in the frame of CATRENE CA701 H-INCEPTION Project

# Conclusions

- State-of-the-art for MEMS applications simulation
  - **Co-simulation**  
*MEMS as FEM models + TLM VP on Linux* : Too much compute-greedy
  - **Co-emulation**  
*MEMS on daughter board + TLM VP on Linux* : Too many boards, tough reproducibility
- SystemC AMS-TLM Virtual Platform assembled and validated
- Next steps
  - Exploit the methodology for new projects during their architecture definition phase
  - Reuse the methodology for new projects with Multi-physical domains + Analog + Digital + SW parts